



PATENT  
Attorney Docket No.: COOL-00901

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	)	Group Art Unit: 3744
Mark Munch et al.	)	Examiner:
Serial No.: 10/643,641	)	<b><u>TRANSMITTAL LETTER</u></b>
Filed: August 18, 2003	)	162 N. Wolfe Road
For: <b>REMEDIES TO PREVENT</b>	)	Sunnyvale, CA 94086
<b>CRACKING IN A LIQUID</b>	)	(408) 530-9700
<b>SYSTEM</b>	)	Customer No.: 28960

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #57607); (EFS ID #57608); and (EFS ID #57610) filed on March 22, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,  
HAVERSTOCK & OWENS LLP

Dated: 3-23-04

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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #57607); (EFS ID #57608); and (EFS ID #57610). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
- Japanese Patent Abstract JP 2000-277540;
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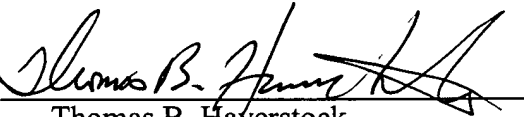


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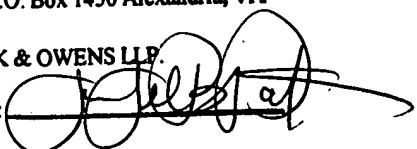
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Date Considered:

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Serial No.: 10/643,641

**INFORMATION DISCLOSURE STATEMENT BY APPLICANT**  
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Applicants: Mark Munch et al.

(37 CFR § 1.98(b))

Filing Date: August 18, 2003

Group Art Unit: 3744

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Filing Date: August 18, 2003

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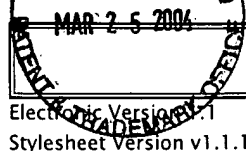
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Submission Type:	Information Disclosure Statement										
Application Number:	10/643641	*10/643641*									
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## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Confirmation Number:	4440						
First Named Applicant:	Mark Munch						
Attorney Docket Number:							
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	1	6146103	2000-11-14	Lee et al.			
	2	6154363	2000-11-28	Chang			
	3	6159353	2000-12-12	West et al.			
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	5	6174675	2001-01-16	Chow et al.	B1		
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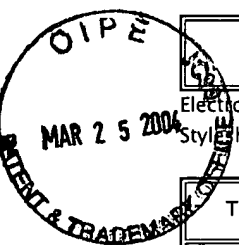
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First Named Applicant: Mark Munch

Attorney Docket Number:

Timestamp: 2004-03-22 18:09:05 EDT

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File Listing:

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3/22/2004

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Page 2 of 2

Doc. Name	File Name	Size (Bytes)
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TRANSMITTAL							
Electronic Version v1.1 Stylesheet Version v1.1.0							
<b>Title of Invention</b>	<b>REMEDIES TO PREVENT CRACKING IN A LIQUID SYSTEM</b>						
Application Number:	10/643641 *10/643641*						
Date:	2003-08-18						
First Named Applicant:	Mark Munch						
Confirmation Number:	4440						
Attorney Docket Number:							
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>		Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney
Submitted by:	Elec. Sign.	Sign. Capacity					
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney					

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Comments	

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	REMEDIES TO PREVENT CRACKING IN A LIQUID SYSTEM						
Application Number:	10/643641	*10/643641*					
Confirmation Number:	4440						
First Named Applicant:	Mark Munch						
Attorney Docket Number:							
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US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	3654988	1972-04-11	Clayton, III			
	2	3817321	1974-06-18	von Cube et al.			
	3	3823572	1974-07-16	Cochran, Jr.			
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35	5219278	1993-06-15	Van Lintel
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50	5459099	1995-10-17	Hsu

Signature

Examiner Name	Date

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Title of Invention

REMEDIES TO PREVENT CRACKING IN A LIQUID SYSTEM

Submission Type: Information Disclosure Statement

Application Number: 10/643641

\*10/643641\*

EFS ID: 57608

Server Response:

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First Named Applicant: Mark Munch

Attorney Docket Number:

Timestamp: 2004-03-22 18:10:49 EDT

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Submitted by:	Elec. Sign.	Sign. Capacity					
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney					

Documents being submitted	Files
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<b>Comments</b>	

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Search string:	( 5508234 or 5514832 or 5514906 or 5544696 or 5548605 or 5575929 or 5585069 or 5641400 or 5692558 or 5696405 or 5727618 or 5774779 or 5703536 or 5704416 or 5759014 or 5763951 or 5800690 or 5801442 or 5835345 or 5836750 or 5858188 or 5863708 or 5870823 or 5874795 or 5876655 or 5880524 or 5901037 or 5936192 or 5940270 or 5942093 or 5964092 or 5965001 or 5965813 or 5978220 or 5997713 or 5998240 or 6007309 or 6010316 or 6013164 or 6019882 or 6054034 or 6068752 or 6090251 or 6096656 or 6100541 or 6101715 or 6126723 or 6129145 or 6129260 or 6131650 ).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date